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Thermal packaging design expert joins embedded thermoelectric cooler manufacturer...

New SENIOR TECHNICAL FELLOW APPOINTED AT NEXTREME THERMAL SOLUTIONS

Research Triangle Park, N.C. (January 22, 2007) – Nextreme Thermal Solutions, the leading manufacturer of thin film thermoelectric components designed to address the most advanced thermal management needs of the electronics, photonics, bio-tech and defense/aerospace industries, has recently named Dr. Phil Deane as Senior Technology Fellow. Dr. Deane, formerly the Director of Packaging for the Advanced Optoelectronic Components Group at JDS Uniphase, joins Nextreme to address thermal management and thermoelectric packaging issues. Dr. Deane will define product and packaging strategies for insertion of Nextreme thermoelectric coolers into customer's products.

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"I am pleased to announce the addition of Dr. Deane to our thermoelectric packaging group," said Dr. Jesko von Windheim, CEO of Nextreme. "Dr. Deane is a luminary in his field. With his wealth of advanced packaging and interconnect knowledge in both the electronic components and optoelectronic components arenas, he will be instrumental in developing new packaging solutions to solve our customers' most challenging thermal problems."

Dr. Deane began his career at AT&T Bell Labs as an engineer working in advanced electronic component packaging. After Bell Labs, he served as the Director of the Advanced Packaging Group at MCNC – a microtechnology think tank located in Research Triangle Park in North Carolina. Dr. Deane went on to become a principal in Optical Process Technologies which was acquired by JDS Uniphase in 2000.

"I am very excited about joining Nextreme," said Dr. Deane. "Nextreme's thin film thermoelectric technology represents a radically new way to achieve in-package cooling. At Nextreme, I look forward to working closely with customers to develop a new packaging approach to address ever increasing thermal problems that are limiting progress in electronic and optical designs."

The demand for small, compact electronic devices with increased capabilities and functionality is a driving force in today's technology markets. Whether the device is manufactured for the consumer, military, aerospace, medical, communications or automotive markets, their evolutionary path is the same — smaller and faster with more functionality. While this trend is well supported by ongoing improvements in semiconductor processing technology, it is broadly recognized that an emerging gate to the evolution of the semiconductor industry will be heat management.

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As a result, there is a compelling need for new packaging strategies that can deal with the ever increasing thermal problem. Nextreme's thin film thermoelectric cooler, which is no larger than a piece of confetti, represents such a strategy – providing a new approach to actively cool electronic and optoelectronic devices at the source, within the constraints of the demand for smaller, low profile components.

Dr. Deane graduated from the University of North Carolina at Chapel Hill in 1984 with a PhD in physics. He has published more than 30 technical papers and holds numerous patents in the electronic packaging field. Dr. Deane is also a member of IEEE and IMAPS.

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About Nextreme Thermal Solutions

Nextreme Thermal Solutions manufactures advanced thin film thermoelectric components to address the thermal management needs of the semiconductor, photonics, test-and-measurement and defense/aerospace industries. These high-performance solid-state components operate as miniature heat pumps for cooling semiconductors and other electronics, and for thermal management of fiber-optic laser controls and integrated optoelectronics. Nextreme's unique thin-film technology provides an industry first - the embedding of an active cooling device in close proximity to the die of an integrated circuit. Other applications include converting heat into electricity for advanced power generation applications, thermal batteries and automotive energy management.

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